AMENDMENTS

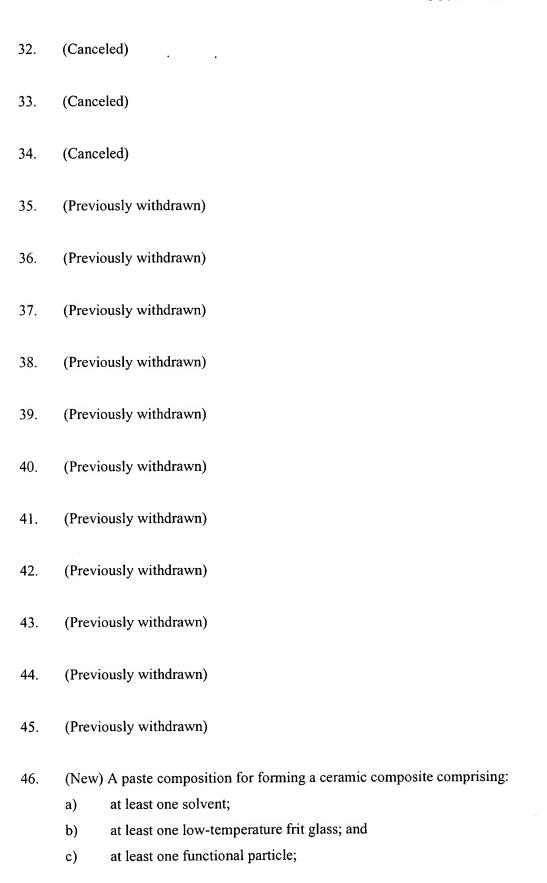
In the claims:

- 1. (Previously withdrawn)
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26.	(Canceled)
27.	(Canceled)
28.	(Canceled)
29.	(Canceled)
30.	(Canceled)

(Canceled)

31.



wherein the paste composition is capable of being directly deposited onto a plastic substrate and wherein the at least one low-temperature frit glass has a melting point low enough that the paste composition is capable of being subsequently processed under conditions effective to provide a composite without inflicting heat related damage to the plastic substrate.

- 47. (New) The paste composition of Claim 46, further comprising d) at least one binder.
- 48. (New) The paste composition of claim 46, wherein the paste is capable of forming a "0-3 composite" ceramic element.
- 49. (New) The paste composition of claim 46, wherein the paste is capable of being deposited onto a substrate by a miniaturized pen.
- 50. (New) The paste composition of claim 46, wherein the solvent is selected from the group consisting of terpineol, dimethyl acetimide, ethylene glycol, a glyme based solvent, alkanol, butyl acetate and mixtures thereof.
- 51. (New) The paste composition of claim 46, wherein the low-temperature frit glass comprises lead.
- 52. (New) The paste composition of claim 46, wherein the at least one functional particle alters a physical property of the frit glass.
- 53. (New) The paste composition of claim 52, wherein the at least one functional particle raises the melting point of the frit glass.
- 54. (New) The paste composition of claim 46, wherein the at least one functional particle is suitable to provide a desired electronic component.
- 55. (New) The paste composition of claim 54, wherein the functional particle comprises a ruthenium-based resistor material, a dielectric capacitance material, or a ferromagnetic based inductor material.

- 56. (New) The paste composition of claim 46, wherein the at least one functional particle is selected from the group consisting of a secondary particle, molecular precursor, and a frit glass modifier.
- 57. (New) The paste composition of claim 46, wherein the conditions effective to provide a composite comprise a conventional low temperature processing method.
- 58. (New) The paste composition of claim 46, wherein the conventional low temperature processing method is a sintering method.
- 59. (New) The paste composition of claim 46, wherein the conditions effective to provide a composite comprise a laser processing method.
- 60. (New) The paste composition of claim 47, wherein the at least one binder comprises at least one sol-gel precursor.
- 61. (New) The paste composition of claim 60, wherein the at least one sol-gel precursor is a metal alkoxide.